



**PRINTED CIRCUIT BOARDS**  
**INTERCONNECTION CARRIERS**

State of the Art: PCB's

Revisio

Datum:

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01

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**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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04 161 FR4 100 L71.70 P18\_10

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

04\_161\_FR4\_100\_L71.70\_p18\_10

Layers	in $\mu$	Material	Build-Up	Assembly	
<b>Layer-1</b>	100 $\mu$	Copper			
	100 $\mu$	Prepreg			(PrePreg-Type: 2116)
	180 $\mu$	Prepreg			(PrePreg-Type: 7628)
<b>Layer-2</b>	70 $\mu$	Copper			
	710 $\mu$	L-FR4			
<b>Layer-3</b>	70 $\mu$	Copper			
	180 $\mu$	Prepreg			
	100 $\mu$	Prepreg			
<b>Layer-99</b>	100 $\mu$	Copper			

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